



## IC Knowledge – MEMS Cost Model Supported Products List

As of December 11, 2008 the following Packages are included in the MEMS Cost Model.

1. None
2. cBGA 32 pin ceramic package with 1 die
3. cLCC 8 pin ceramic package with 1 die
4. cSOIC 8 with cap ceramic package for 1 die
5. DIP 8 pin with pressure port for 1 die
6. EPCOS' CSSPlus with 2 die
7. Knowles S575B MEMS Microphone with 2 die (1 MEMS + 1 IC)
8. PLCC 44 pin package with 2 die (1 MEMS + 1 IC)
9. QFN 4 pin package 2.0mm x 2.5mm with 2 die (1 MEMS + 1 IC)
10. QFN 4 pin package 2.5mm x 5.0mm with 2 die (1 MEMS + 1 IC)
11. QFN 16 pin plastic package with 1 die
12. QFN 40 pin plastic package with 1 die
13. SOIC 14 pin package with 2 die (1 MEMS + 1 IC)
14. SOIC 16 pin package with 2 die (1 MEMS + 1 IC)
15. SOP 52 pin package with 2 die (1 MEMS + 1 IC)
16. TI DLP gold ceramic package with optical window